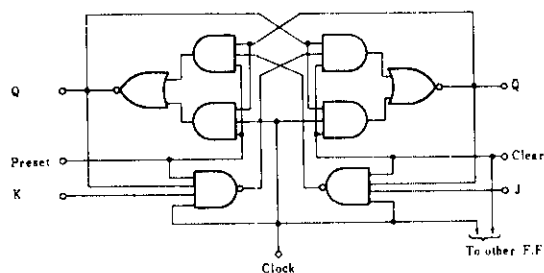
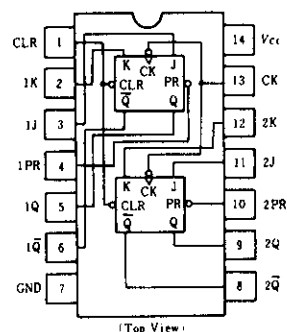


HD74LS114 • Dual J-K Negative-edge-triggered Flip-Flops (with Preset, Common Clear and Common Clock)

■ BLOCK DIAGRAM (1/2)



■ PIN ARRANGEMENT



■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Clock frequency	f_{clock}	0	—	30	MHz
Pulse width	Clock High	20	—	—	ns
	Preset Clear Low	25	—	—	ns
Setup time	"H" Data	20↓	—	—	ns
	"L" Data	20↓	—	—	ns
Hold time	t_h	0↓	—	—	ns

Note) ↓; The arrow indicates the falling edge.

■ FUNCTION TABLE

Inputs					Outputs	
Preset	Clear	Clock	J	K	Q	$\bar{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H*	H*
H	H	↓	L	L	Q_0	$\bar{Q}_0$
H	H	↓	H	L	H	L
H	H	↓	L	H	L	H
H	H	↓	H	H	Toggle	
H	H	H	X	X	Q_0	$\bar{Q}_0$

Notes) H; high level, L; low level, X; irrelevant

↓; transition from high to low level

Q_0 ; level of Q before the indicated steady-state input conditions were established.

$\bar{Q}_0$; complement of Q_0 or level of $\bar{Q}$ before the indicated steady-state input conditions were established.

Toggle; each output changes to the complement of its previous level on each active transition indicated by ↓.

*; This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (high) level.

HD74LS114

■ ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

Item		Symbol	Test Conditions	min	typ*	max	Unit
Input voltage		V_{IH}		2.0	—	—	V
		V_{IL}		—	—	0.8	V
Output voltage		V_{OH}	$V_{CC} = 4.75\text{V}$, $V_{IH} = 2\text{V}$, $V_{IL} = 0.8\text{V}$, $I_{OH} = -400\mu\text{A}$	2.7	—	—	V
		V_{OL}	$V_{CC} = 4.75\text{V}$, $V_{IL} = 0.8\text{V}$, $I_{OL} = 8\text{mA}$	—	—	0.5	V
			$V_{IH} = 2\text{V}$, $I_{OL} = 4\text{mA}$	—	—	0.4	
Input current	J, K	I_{IH}	$V_{CC} = 5.25\text{V}$, $V_I = 2.7\text{V}$	—	—	20	μA
	Clear			—	—	120	
	Preset			—	—	60	
	Clock			—	—	160	
	J, K	I_{IL}^{**}	$V_{CC} = 5.25\text{V}$, $V_I = 0.4\text{V}$	—	—	-0.4	mA
	Clear			—	—	-1.6	
	Preset			—	—	-0.8	
	Clock			—	—	-1.6	
	J, K	I_I	$V_{CC} = 5.25\text{V}$, $V_I = 7\text{V}$	—	—	0.1	mA
	Clear			—	—	0.6	
	Preset			—	—	0.3	
	Clock			—	—	0.8	
Short-circuit output current		I_{OS}	$V_{CC} = 5.25\text{V}$	-20	—	-100	mA
Supply current ***		I_{CC}	$V_{CC} = 5.25\text{V}$	—	4	8	mA
Input clamp voltage		V_{IK}	$V_{CC} = 4.75\text{V}$, $I_{IS} = -18\text{mA}$	—	—	-1.5	V

* $V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$

** I_{IL} should not be measured when preset and clear inputs are low at same time.

*** With all outputs open, I_{CC} is measured with the Q and $\bar{Q}$ output high in turn. At the time of measurement, the clock input is grounded.

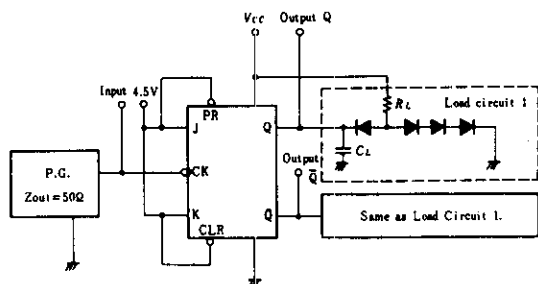
■ SWITCHING CHARACTERISTICS ($V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$)

Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Maximum clock frequency	f_{max}			$C_L = 15\text{pF}, R_L = 2\text{k}\Omega$	30	45	—	MHz
Propagation delay time	t_{PLH}	Clear Preset Clock	Q, $\bar{Q}$		—	11	20	ns
	t_{PHL}				—	15	30	ns

■ TESTING METHOD

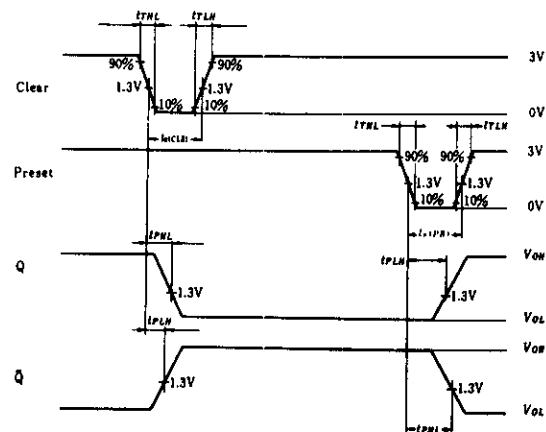
1) Test Circuit

1.1) f_{max} , t_{PLH} , t_{PHL} (Clock $\rightarrow$ Q, $\bar{Q}$)



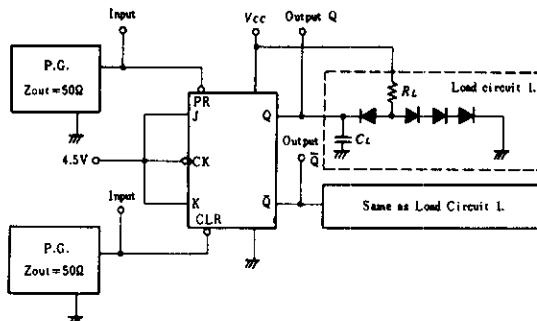
- Notes) 1. Test is put into the each flip-flop.
2. All diodes are 1S2074 (B).
3. C_L includes probe and jig capacitance.

Waveform



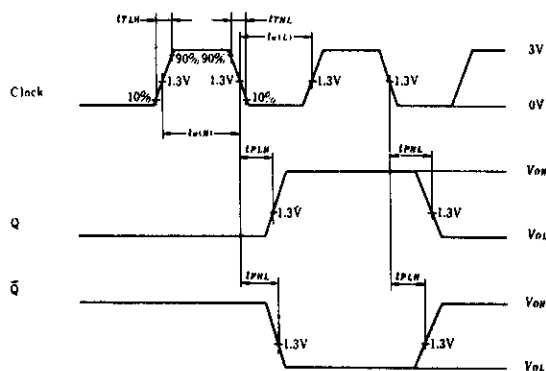
- Note) Clock input pulse; $t_{TLH} \leq 15\text{ns}$, $t_{THL} \leq 6\text{ns}$, $PRR=1\text{MHz}$, duty cycle=50% and: for f_{max} , $t_{TLH}=t_{THL} \leq 2.5\text{ns}$.

1.2) t_{PHL} , t_{PLH} (Clear, Preset $\rightarrow$ Q, $\bar{Q}$)



- Notes) 1. Test is put into the each flip-flop.
2. All diodes are 1S2074 (B).
3. C_L includes probe and jig capacitance.

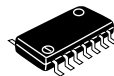
Waveform



- Note) Clear and preset input pulse: $t_{TLH} \leq 15\text{ns}$, $t_{THL} \leq 6\text{ns}$, $PRR=1\text{MHz}$



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g



Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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